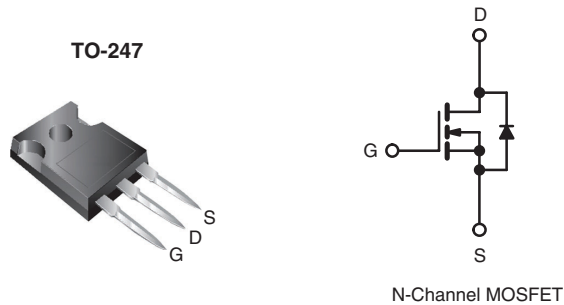


## Power MOSFET

PRODUCT SUMMARY		
$V_{DS}$ (V)	1000	
$R_{DS(on)}$ ( $\Omega$ )	$V_{GS} = 10$ V	5.0
$Q_g$ (Max.) (nC)	80	
$Q_{gs}$ (nC)	10	
$Q_{gd}$ (nC)	42	
Configuration	Single	



### FEATURES

- Dynamic  $dV/dt$  Rating
- Repetitive Avalanche Rated
- Isolated Central Mounting Hole
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Lead (Pb)-free



### DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-247 package is preferred for commercial-industrial applications where higher power levels preclude the use of TO-220 devices. The TO-247 is similar but superior to the earlier TO-218 package because of its isolated mounting hole. It also provides greater creepage distance between pins to meet the requirements of most safety specifications.

ORDERING INFORMATION	
Package	TO-247
Lead (Pb)-free	IRFPG30PbF
	SiHFPG30-E3
SnPb	IRFPG30
	SiHFPG30

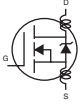
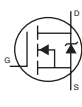
ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherwise noted			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	$V_{DS}$	1000	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current	$I_D$	$T_C = 25$ °C	3.1
		$T_C = 100$ °C	2.0
Pulsed Drain Current <sup>a</sup>	$I_{DM}$	12	A
Linear Derating Factor		1.0	W/°C
Single Pulse Avalanche Energy <sup>b</sup>	$E_{AS}$	180	mJ
Repetitive Avalanche Current <sup>a</sup>	$I_{AR}$	3.1	A
Repetitive Avalanche Energy <sup>a</sup>	$E_{AR}$	13	mJ
Maximum Power Dissipation	$P_D$	125	W
Peak Diode Recovery $dV/dt^c$	$dV/dt$	1.0	V/ns
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to + 150	°C
Soldering Recommendations (Peak Temperature)	for 10 s	300 <sup>d</sup>	
Mounting Torque	6-32 or M3 screw		10
			1.1

#### Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 50$  V, starting  $T_J = 25$  °C,  $L = 35$  mH,  $R_G = 25$   $\Omega$ ,  $I_{AS} = 3.1$  A (see fig. 12).
- $I_{SD} \leq 3.1$  A,  $dI/dt \leq 80$  A/ $\mu$ s,  $V_{DD} \leq 600$ ,  $T_J \leq 150$  °C.
- 1.6 mm from case.

\* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	$R_{thJA}$	-	40	°C/W
Case-to-Sink, Flat, Greased Surface	$R_{thCS}$	0.24	-	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	1.0	

SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}$ , $I_D = 250\text{ }\mu\text{A}$	1000	-	-	V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$ , $I_D = 1\text{ mA}$	-	1.4	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	2.0	-	4.0	V
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20\text{ V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 1000\text{ V}$ , $V_{GS} = 0\text{ V}$	-	-	100	$\mu\text{A}$
		$V_{DS} = 800\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_J = 125\text{ }^\circ\text{C}$	-	-	500	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$   $I_D = 1.9\text{ A}^b$	-	-	5.0	$\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS} = 50\text{ V}$ , $I_D = 1.9\text{ A}^b$	2.4	-	-	S
<b>Dynamic</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}$ , $V_{DS} = 25\text{ V}$ , $f = 1.0\text{ MHz}$ , see fig. 5	-	980	-	pF
Output Capacitance	$C_{oss}$		-	140	-	
Reverse Transfer Capacitance	$C_{rss}$		-	50	-	
Total Gate Charge	$Q_g$	$V_{GS} = 10\text{ V}$   $I_D = 3.1\text{ A}$ , $V_{DS} = 400\text{ V}$ see fig. 6 and 13 <sup>b</sup>	-	-	80	nC
Gate-Source Charge	$Q_{gs}$		-	-	10	
Gate-Drain Charge	$Q_{gd}$		-	-	42	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 500\text{ V}$ , $I_D = 3.1\text{ A}$ , $R_G = 12\text{ }\Omega$ , $R_D = 170\text{ }\Omega$ , see fig. 10 <sup>b</sup>	-	12	-	ns
Rise Time	$t_r$		-	24	-	
Turn-Off Delay Time	$t_{d(off)}$		-	89	-	
Fall Time	$t_f$		-	29	-	
Internal Drain Inductance	$L_D$	Between lead, 6 mm (0.25") from package and center of die contact 	-	5.0	-	nH
Internal Source Inductance	$L_S$		-	13	-	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	3.1	A
Pulsed Diode Forward Current <sup>a</sup>	$I_{SM}$		-	-	12	
Body Diode Voltage	$V_{SD}$	$T_J = 25\text{ }^\circ\text{C}$ , $I_S = 3.1\text{ A}$ , $V_{GS} = 0\text{ V}^b$	-	-	1.8	V
Body Diode Reverse Recovery Time	$t_{rr}$	$T_J = 25\text{ }^\circ\text{C}$ , $I_F = 3.1\text{ A}$ , $dI/dt = 100\text{ A}/\mu\text{s}^b$	-	410	620	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	1.3	2.0	$\mu\text{C}$
Forward Turn-On Time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )				

**Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).  
b. Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted

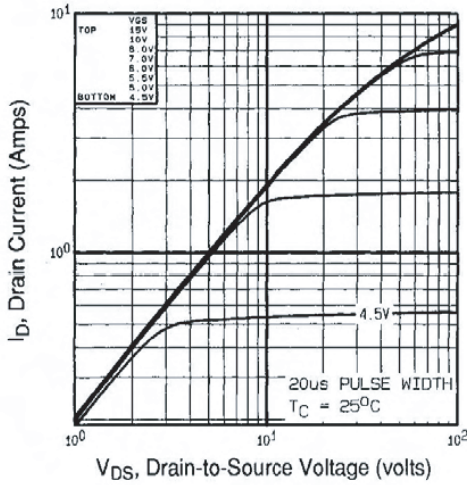


Fig. 1 - Typical Output Characteristics,  $T_C = 25\text{ }^\circ\text{C}$

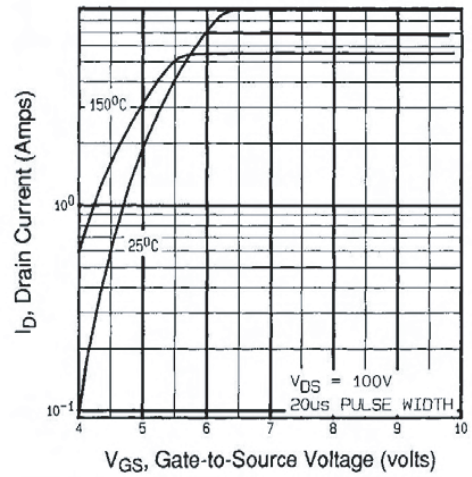


Fig. 3 - Typical Transfer Characteristics

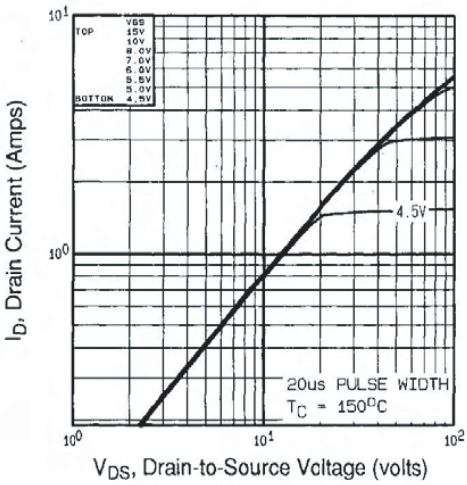


Fig. 2 - Typical Output Characteristics,  $T_C = 150\text{ }^\circ\text{C}$

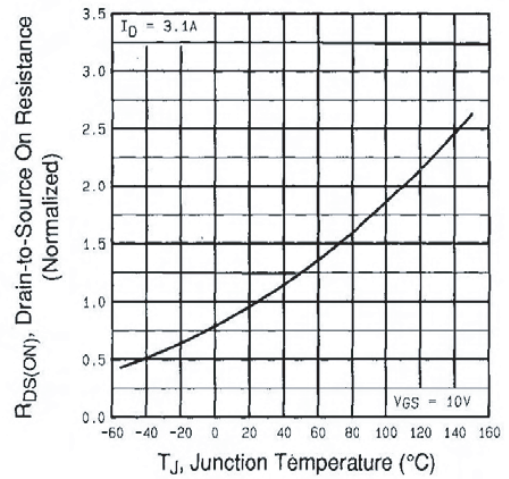


Fig. 4 - Normalized On-Resistance vs. Temperature

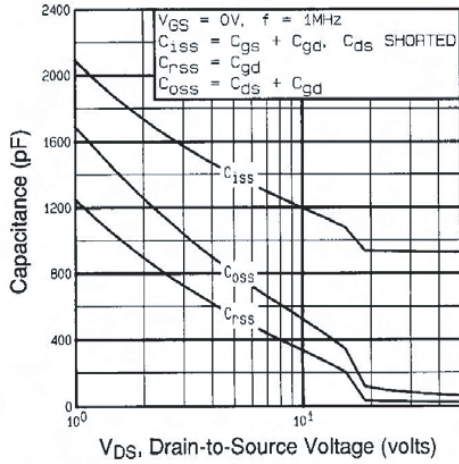


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

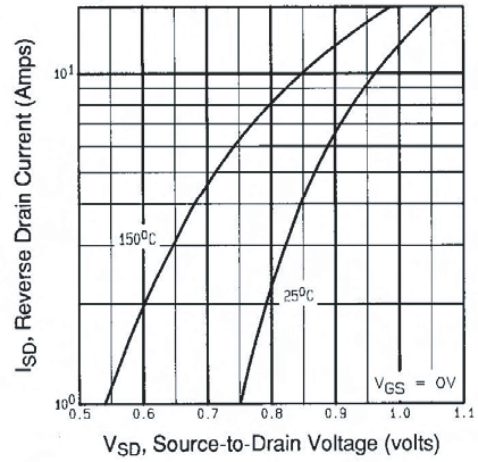


Fig. 7 - Typical Source-Drain Diode Forward Voltage

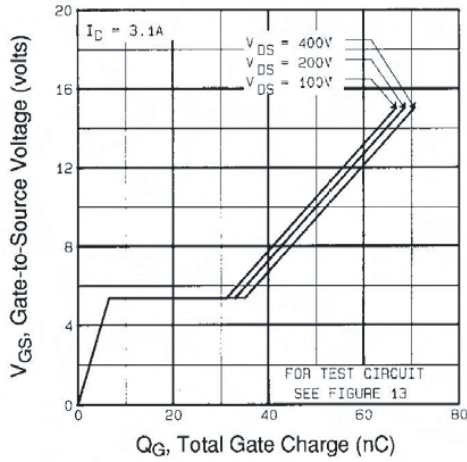


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

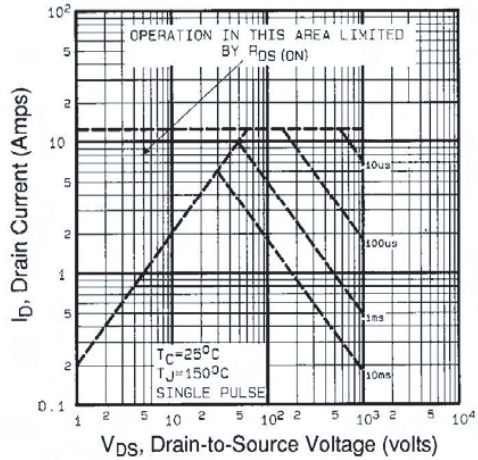


Fig. 8 - Maximum Safe Operating Area

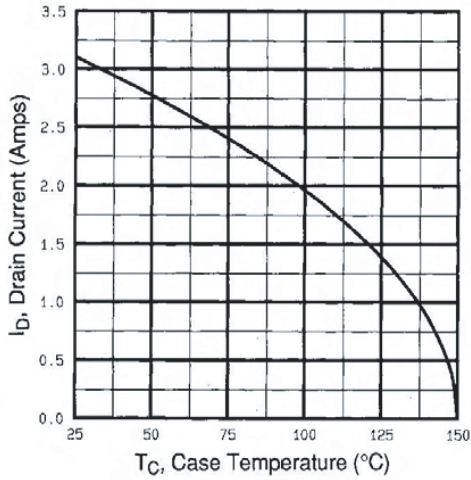


Fig. 9 - Maximum Drain Current vs. Case Temperature

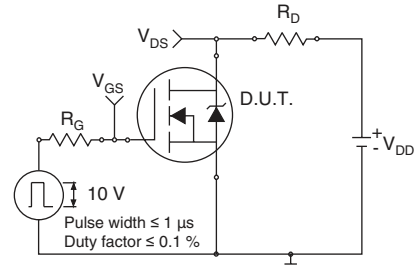


Fig. 10a - Switching Time Test Circuit

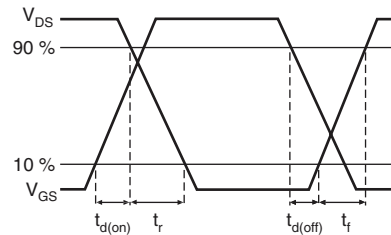


Fig. 10b - Switching Time Waveforms

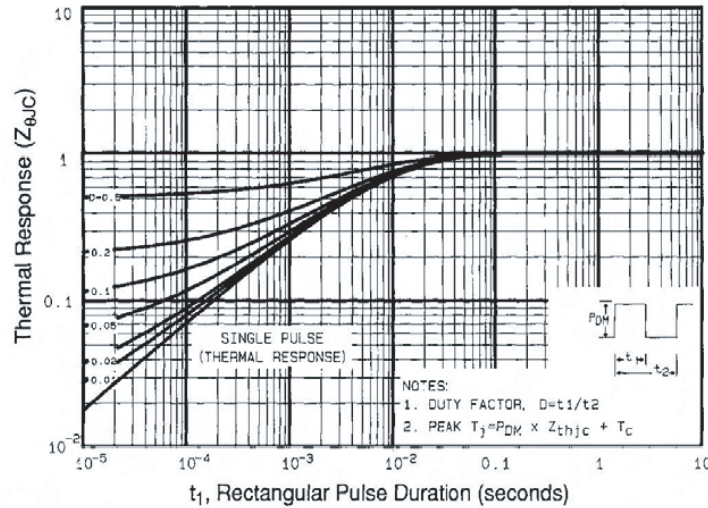


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

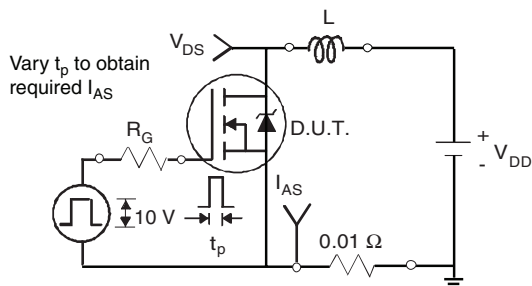


Fig. 12a - Unclamped Inductive Test Circuit

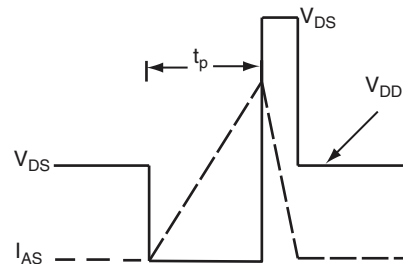


Fig. 12b - Unclamped Inductive Waveforms

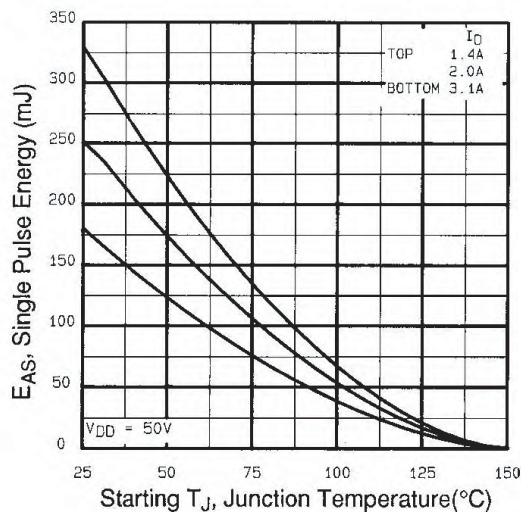


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

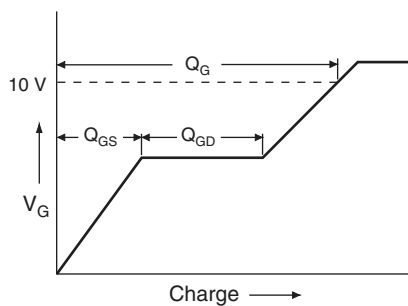


Fig. 13a - Basic Gate Charge Waveform

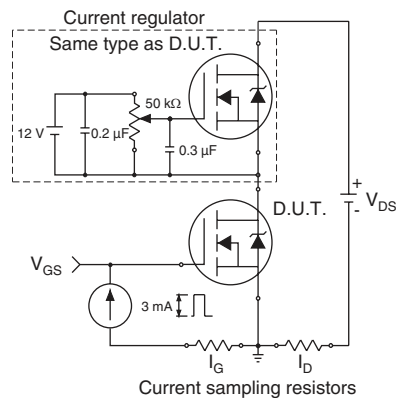
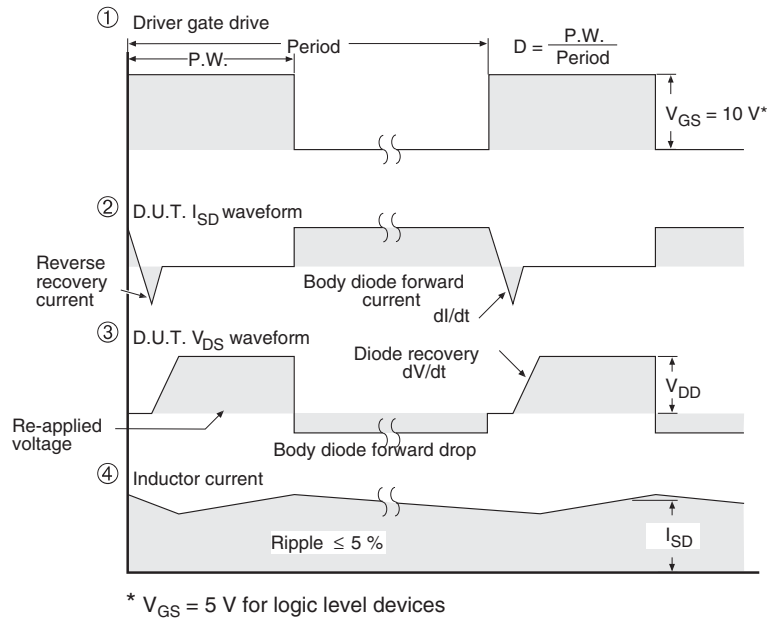
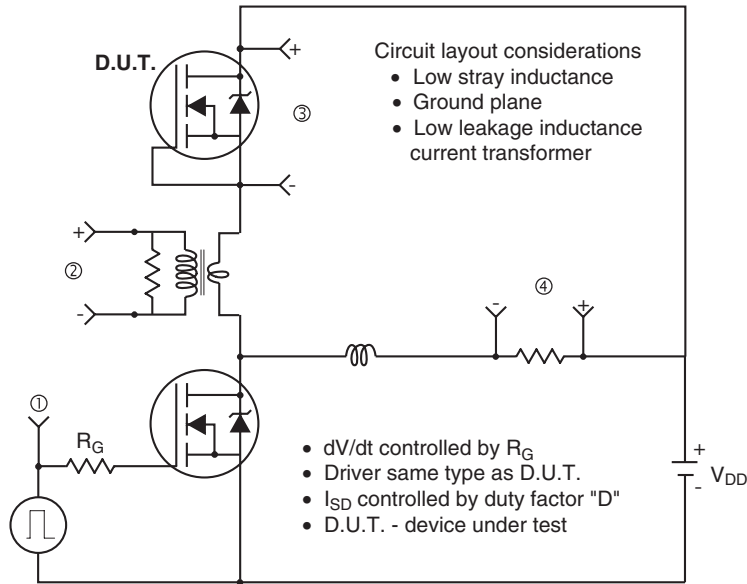


Fig. 13b - Gate Charge Test Circuit

## Peak Diode Recovery $dV/dt$ Test Circuit



**Fig. 14 - For N-Channel**

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